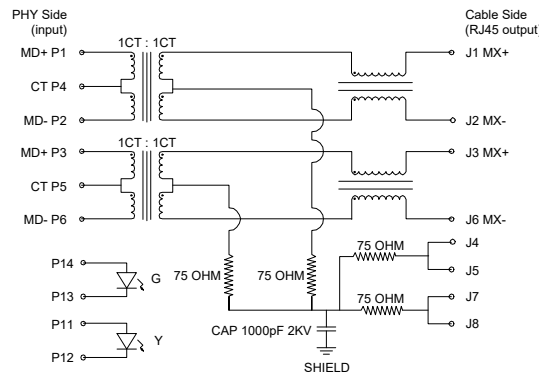
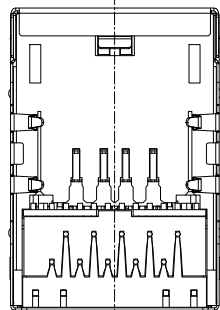
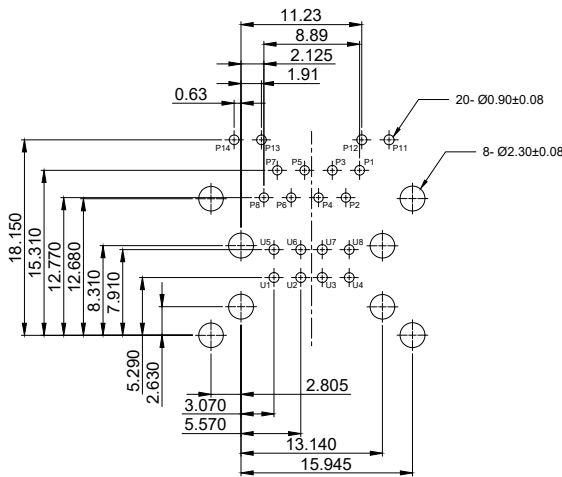


- NOTES:
 MECHANICAL HOUSING & INSERT : THERMOPLASTIC UL94 V-0
 CONTACT : COPPER ALLOY
 PLATING : SELECTIVE GOLD 6u" MIN. IN CONTACT AREA
 SHIELD : SUS304
 USB : THERMOPLASTIC UL94V-0 CONTACT AREA 6u" GOLD PLATING MIN.
- ENVIRONMENTAL STORAGE : -40°C ~ +85°C
 OPERATION : -40°C ~ +85°C

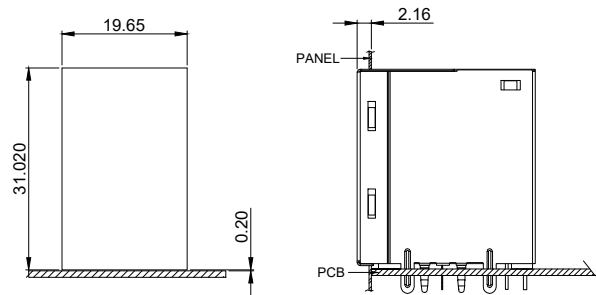


CIRCUIT SCHEMATIC

PARAMETER	SPECIFICATIONS	
TURN RATIO @100KHz	(P1~P2):(J1~J2) = 1:1±5% (P3~P6):(J3~J6) = 1:1±5%	
PRIMARY INDUCTANCE	350uH Min. @100KHz, 0.1V 8mA DC BIAS	
DC RESISTANCE	(J1~J2):(J3~J6) 1.2 OHMS Max.	
INSERTION LOSS	1-100MHz	-1.2dB Max.
	30-60MHz	-16dB Min.
RETURN LOSS	60-80MHz	-10dB Min.
	1-100MHz	-30dB Min.
CROSS TALK	1-100MHz	-30dB Min.
COMMON MODE REJECTION RATIO	1-100MHz	-30dB Min.
ISOLATION PHY SIDE TO LINE SIDE	1500V AC OR 2250V DC	



RECOMMENDED PCB LAYOUT



RECOMMENDED PANEL OPENING

		UNIT	mm
		REVISION	A
PRODUCT		RJ45 + USB ICM 10/100 Base-T	
DWG NO.		PART NO.	
EZI01SU-108N21-01			
PROJECTION	SCALE	SHEET	1 OF 1
		±0.10 UNLESS OTHERWISE SPECIFIED	